

FDS8958

Dual N & P-Channel PowerTrench[®] MOSFET

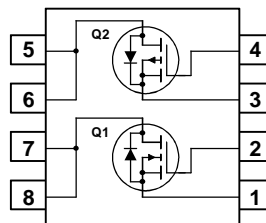
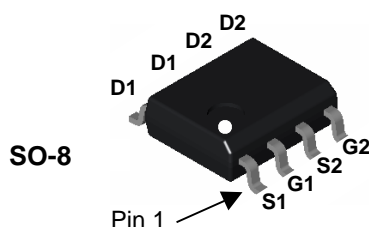
General Description

These dual N- and P-Channel enhancement mode power field effect transistors are produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain superior switching performance.

These devices are well suited for low voltage and battery powered applications where low in-line power loss and fast switching are required.

Features

- **Q1:** N-Channel
7.0A, 30V $R_{DS(on)} = 0.028\Omega @ V_{GS} = 10V$
 $R_{DS(on)} = 0.040\Omega @ V_{GS} = 4.5V$
- **Q2:** P-Channel
-5A, -30V $R_{DS(on)} = 0.052\Omega @ V_{GS} = -10V$
 $R_{DS(on)} = 0.080\Omega @ V_{GS} = -4.5V$
- Fast switching speed
- High power and handling capability in a widely used surface mount package



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Q1	Q2	Units
V_{DSS}	Drain-Source Voltage	30	30	V
V_{GSS}	Gate-Source Voltage	± 20	± 20	V
I_D	Drain Current - Continuous (Note 1a)	7	-5	A
	- Pulsed	20	-20	
P_D	Power Dissipation for Dual Operation	2		W
	Power Dissipation for Single Operation (Note 1a)	1.6		
	(Note 1b)	1		
	(Note 1c)	0.9		
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150		$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	78	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	40	$^\circ\text{C/W}$

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS8958	FDS8958	13"	12mm	2500 units

Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
Off Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$ $V_{GS} = 0\text{ V}, I_D = -250\ \mu\text{A}$	Q1 Q2	30 -30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$, Referenced to 25°C $I_D = -250\ \mu\text{A}$, Referenced to 25°C	Q1 Q2		25 -22		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$ $V_{DS} = -24\text{ V}, V_{GS} = 0\text{ V}$	Q1 Q2			1 -1	μA
I_{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$	All			100	nA
I_{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$	All			-100	nA
On Characteristics (Note 2)							
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$ $V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	Q1 Q2	1 -1	1.6 -1.7	3 -3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$, Referenced to 25°C $I_D = -250\ \mu\text{A}$, Referenced to 25°C	Q1 Q2		-4.3 4		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 7\text{ A}$	Q1		21	28	m Ω
		$V_{GS} = 10\text{ V}, I_D = 7\text{ A}, T_J = 125^\circ\text{C}$			32	42	
		$V_{GS} = 4.5\text{ V}, I_D = 6\text{ A}$			27	40	
		$V_{GS} = -10\text{ V}, I_D = -5\text{ A}$	Q2		41	52	
		$V_{GS} = -10\text{ V}, I_D = -5\text{ A}, T_J = 125^\circ\text{C}$			58	78	
		$V_{GS} = -4.5\text{ V}, I_D = -4\text{ A}$			58	80	
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10\text{ V}, V_{DS} = 5\text{ V}$ $V_{GS} = -10\text{ V}, V_{DS} = -5\text{ V}$	Q1 Q2	20 -20			A
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 7\text{ A}$	Q1		19		S
		$V_{DS} = -5\text{ V}, I_D = -5\text{ A}$	Q2		11		
Dynamic Characteristics							
C_{iss}	Input Capacitance	Q1 $V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	Q1		789		pF
			Q2		690		
C_{oss}	Output Capacitance	Q2	Q1		173		pF
			Q2		306		
C_{rfs}	Reverse Transfer Capacitance	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	Q1		66		pF
			Q2		77		

Electrical Characteristics (continued) $T_A = 25^\circ\text{C}$ unless otherwise noted

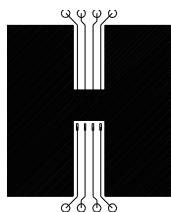
Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
Switching Characteristics (Note 2)							
$t_{d(on)}$	Turn-On Delay Time	Q1 $V_{DD} = 10\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 10\text{ V}, R_{GEN} = 6\ \Omega$	Q1 Q2		6 6.7	12 13.4	ns
t_r	Turn-On Rise Time		Q1 Q2		10 9.7	18 19.4	ns
$t_{d(off)}$	Turn-Off Delay Time	Q2 $V_{DD} = -10\text{ V}, I_D = -1\text{ A},$ $V_{GS} = -10\text{ V}, R_{GEN} = 6\ \Omega$	Q1 Q2		18 19.8	29 35.6	ns
t_f	Turn-Off Fall Time		Q1 Q2		5 12.3	12 22.2	ns
Q_g	Total Gate Charge	Q1 $V_{DS} = 15\text{ V}, I_D = 7\text{ A}, V_{GS} = 10\text{ V}$	Q1 Q2		16 14	26 23	nC
Q_{gs}	Gate-Source Charge		Q1 Q2		2.5 2.2		nC
Q_{gd}	Gate-Drain Charge	Q2 $V_{DS} = -15\text{ V}, I_D = -5\text{ A}, V_{GS} = -10\text{ V}$	Q1 Q2		2.1 1.9		nC

Drain-Source Diode Characteristics and Maximum Ratings

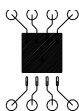
I_S	Maximum Continuous Drain-Source Diode Forward Current		Q1 Q2			1.3 -1.3	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 1.3\text{ A}$ (Note 2) $V_{GS} = 0\text{ V}, I_S = -1.3\text{ A}$ (Note 2)	Q1 Q2		0.74 -0.76	1.2 -1.2	V

Notes:

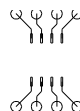
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 78°W when mounted on a 0.5 in^2 pad of 2 oz copper



b) 125°W when mounted on a $.02\text{ in}^2$ pad of 2 oz copper



c) 135°W when mounted on a minimum pad.

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < $300\mu\text{s}$, Duty Cycle < 2.0%

Typical Characteristics: Q1

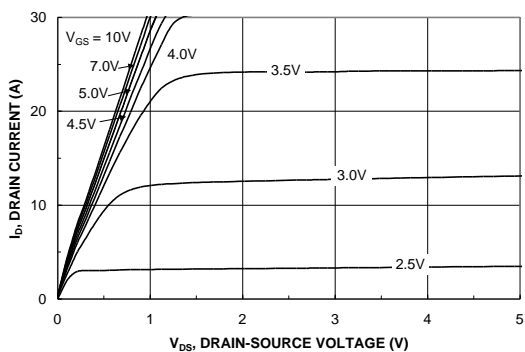


Figure 1. On-Region Characteristics.

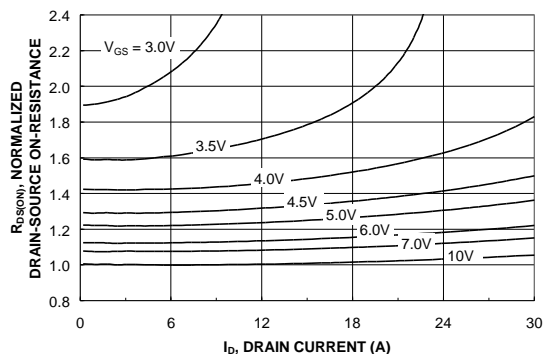


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

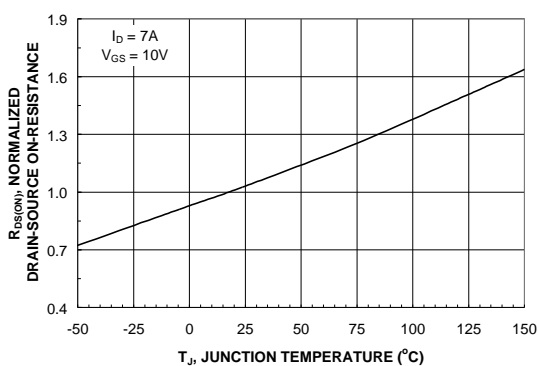


Figure 3. On-Resistance Variation with Temperature.

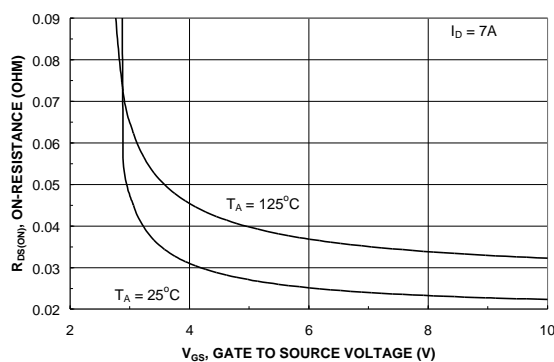


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

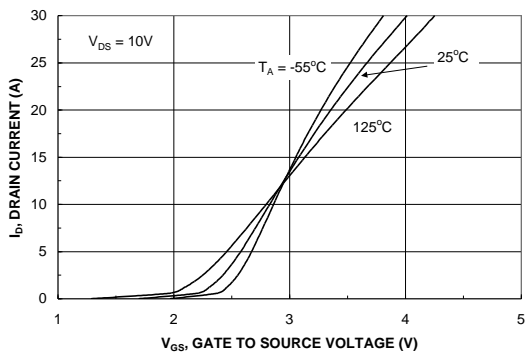


Figure 5. Transfer Characteristics.

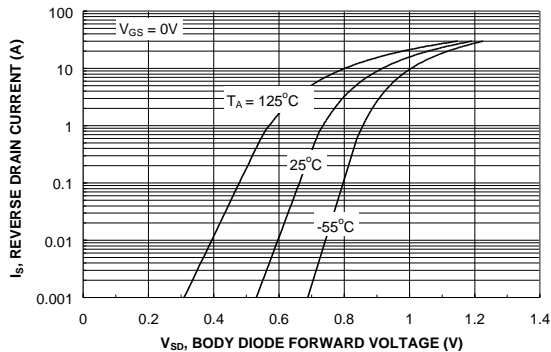


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics: Q1

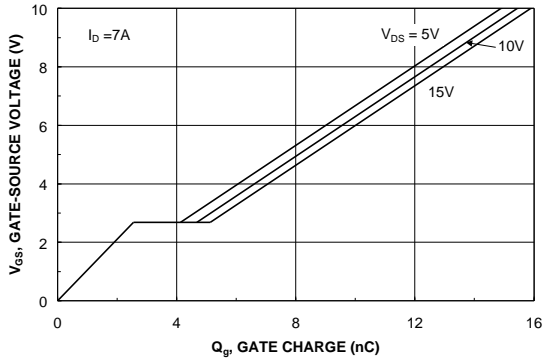


Figure 7. Gate Charge Characteristics.

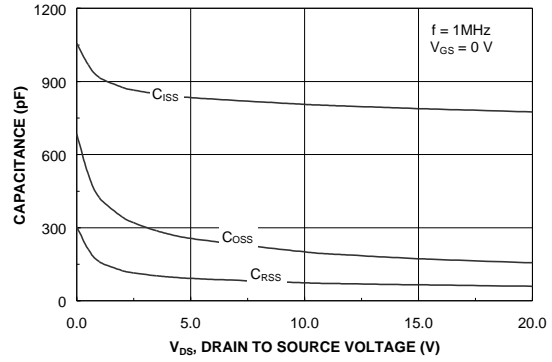


Figure 8. Capacitance Characteristics.

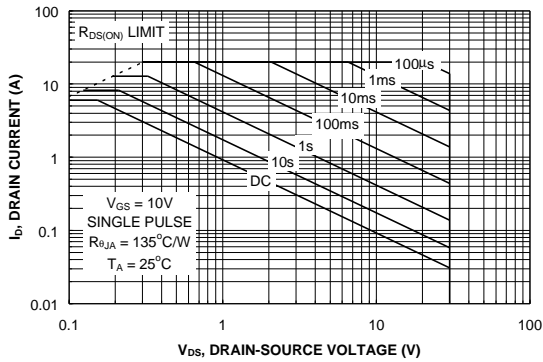


Figure 9. Maximum Safe Operating Area.

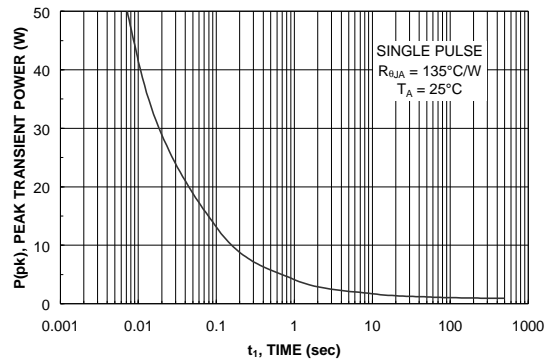


Figure 10. Single Pulse Maximum Power Dissipation.

Typical Characteristics: Q2

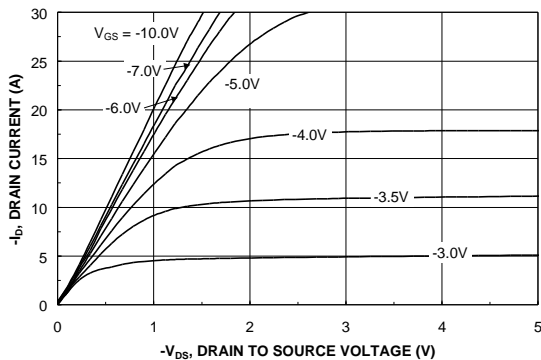


Figure 11. On-Region Characteristics.

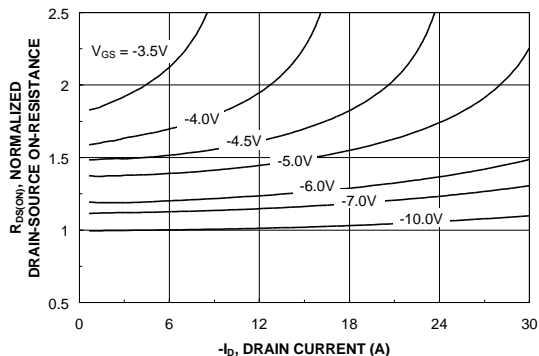


Figure 12. On-Resistance Variation with Drain Current and Gate Voltage.

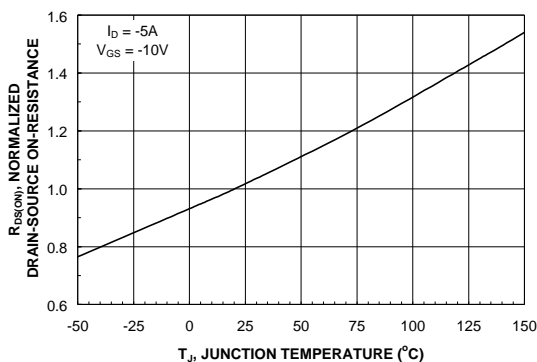


Figure 13. On-Resistance Variation with Temperature.

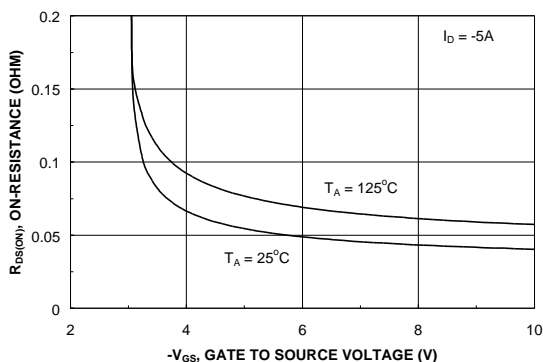


Figure 14. On-Resistance Variation with Gate-to-Source Voltage.

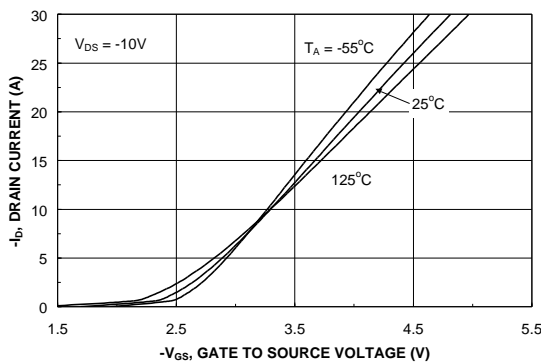


Figure 15. Transfer Characteristics.

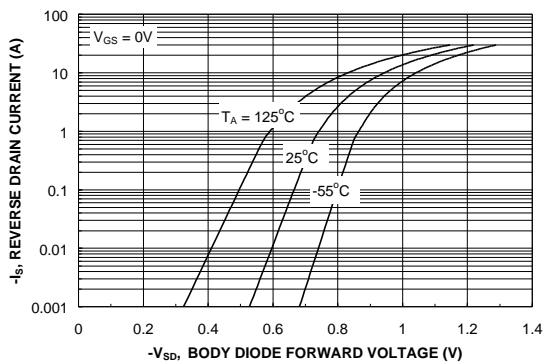


Figure 16. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics: Q2

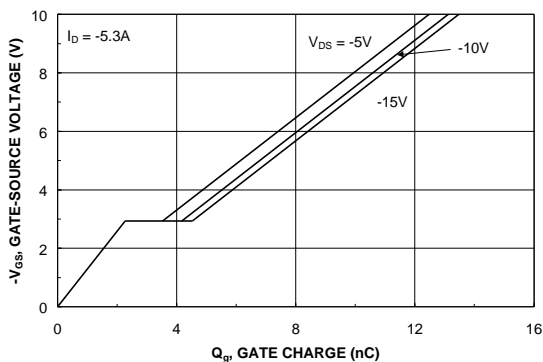


Figure 17. Gate Charge Characteristics.

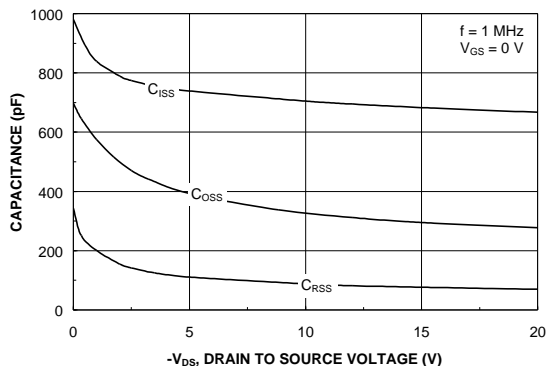


Figure 18. Capacitance Characteristics.

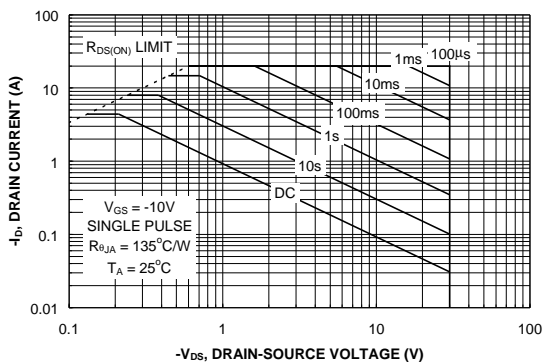


Figure 19. Maximum Safe Operating Area.

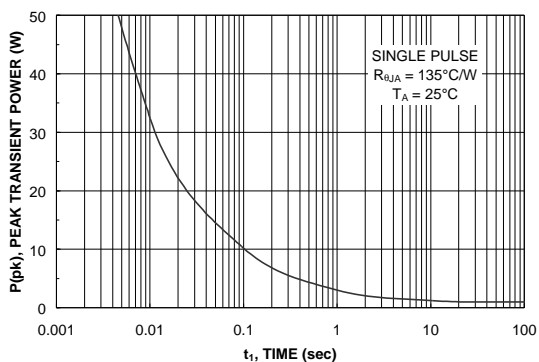


Figure 20. Single Pulse Maximum Power Dissipation.

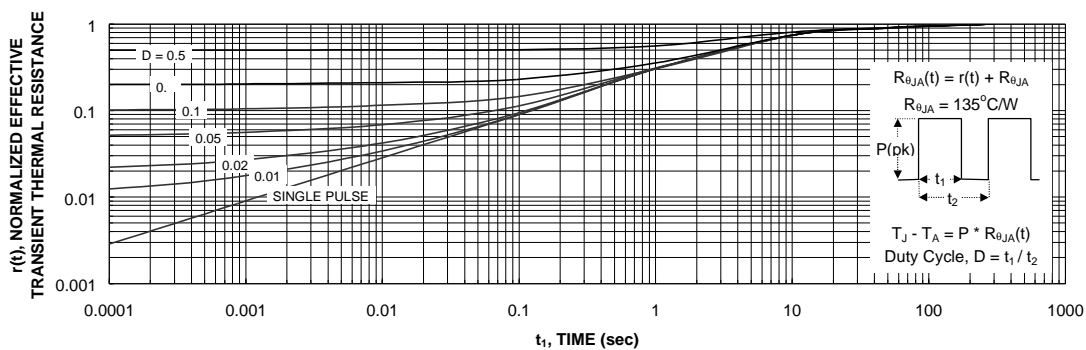


Figure 21. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.

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CROSSVOLT™	GlobalOptoisolator™	MicroPak™	QFET®	SuperSOT™-8
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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

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FDS8958

30V Dual N & P-Channel PowerTrench MOSFET

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Product status/pricing/packaging

BUY

Product	Product status	Pb-free Status	Package type	Leads	Packing method	Package Marking Convention**
FDS8958_NF073	Full Production	 Full Production	SO-8	8	TAPE REEL	Line 1: \$Y (Fairchild logo) &Z (Asm. Plant Code) &2 (2-Digit Date Code) &T (Die Trace Code) Line 2: FDS Line 3: 8958

** A sample button will appear if the part is available through Fairchild's on-line samples program. If there is no sample button, please contact a [Fairchild distributor](#) to obtain samples



Indicates product with Pb-free second-level interconnect. For more information [click here](#).

Package marking information for product FDS8958 is available. [Click here for more information](#).

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Application notes

[AN-4143: LCD Backlight Inverter Drive IC \(FAN7310\)](#) (321 K) Jul 27, 2007
[AN-6016: AN-6016 LCD Backlight Inverter Drive IC \(FAN7311\)](#) (462 K) Jul 27, 2007

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Qualification Support

Click on a product for detailed qualification data

Product
FDS8958_NF073

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